

■ Features

- Molding Inductor.
- Low Profile,Low Temp.
- Large Current(Over 15A).
- Customize For Different Need.
- Operating temperature:-55℃ ~ +125℃.

■ Applications

- General Electronic.
- Video Device,TV,TFT.
- Power Module for PC.
- NB/Lap Top Computer.
- Server,VGA Card/Module.

■ Product Identification

$\frac{\text{YSPI}}{(1)}$
 $\frac{\square\square\square\square\square\square\square\square}{(2)}$
 $-\frac{\square\square\square}{(3)}$
 $\frac{\square}{(4)}$

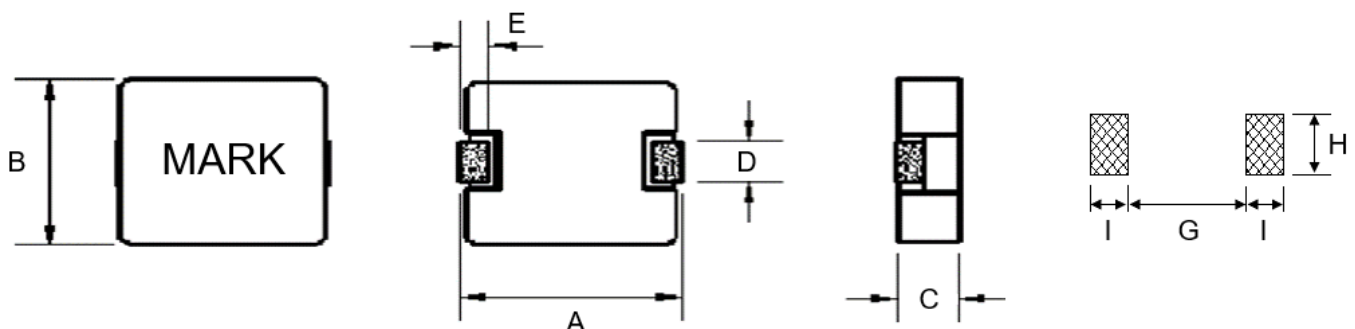
(1) : Type

(2) : Dimensions

(3) : Inductance value

(4) : Inductance Tolerance: N=±30%,M=±20%

■ Shapes and Dimensions (Unit: mm)



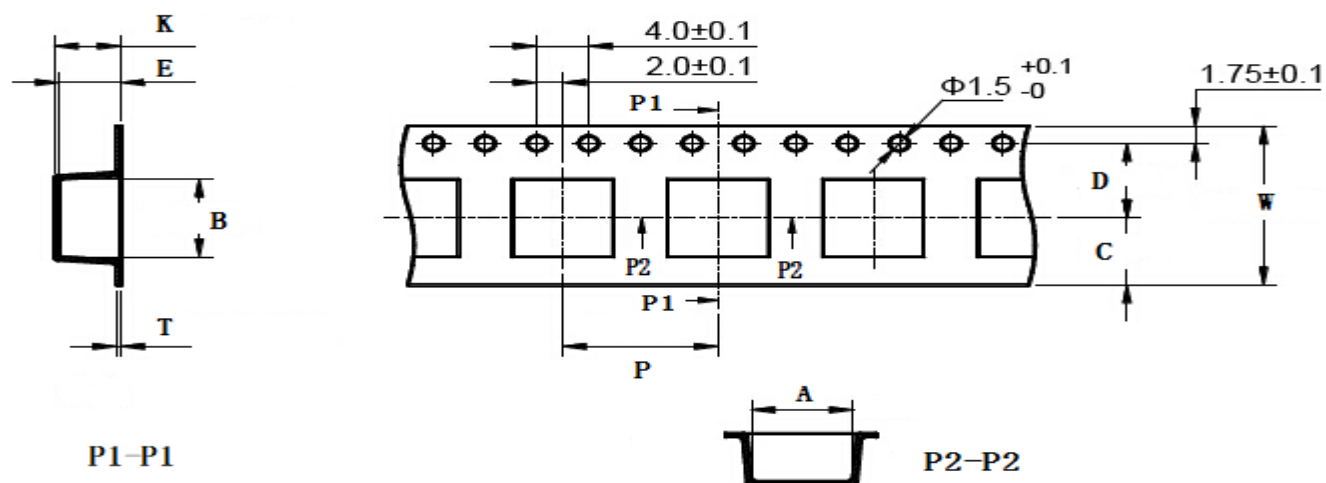
TYPE	A	B	C	D	E	G Ref.	H Ref.	I Ref.
YSPI105840	10.2±0.3	5.6±0.2	3.8±0.2	2.8±0.5	2.2±0.5	4.8	3.5	3.0

■ YSPI105840 Series

Part Number	Inductance (uH) @100KHz	DCR(mΩ)		Heat Rating Current (A)	Saturation Current (A)
		Typ.	Max.		
YSPI105840TP-R15M	0.15±20%	0.57	0.60±7%	45.0	90.0

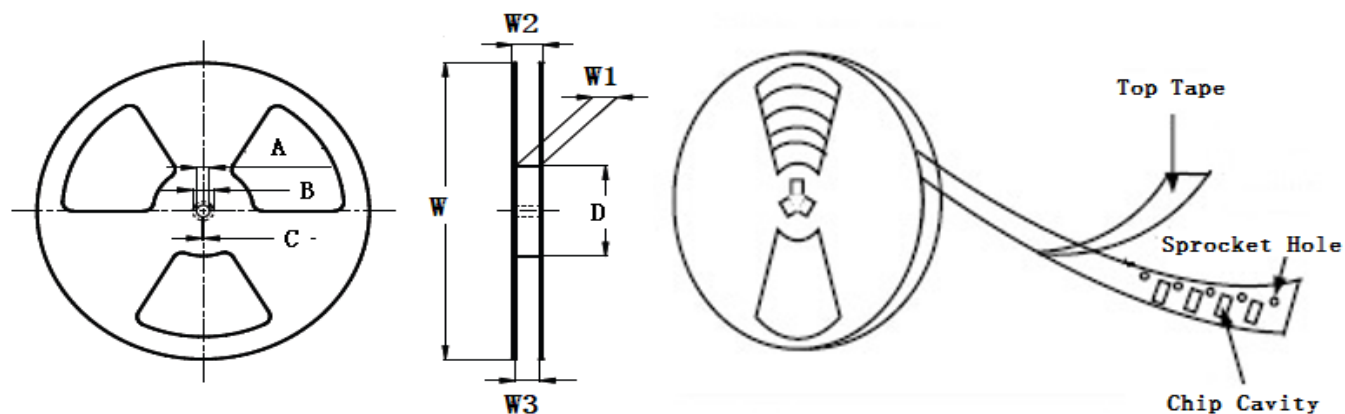
- ※ The saturation current value is the DC current value having inductance decrease down to 30%.(at 20℃)
- ※ The temperature rise current value is the DC current value having temperature increase up to 40℃. (at 20℃)
- ※ The rated current is the DC current value that satisfies both of current value saturation current value and temperature rise current value.

■ Taping Dimensions(Unit:mm)



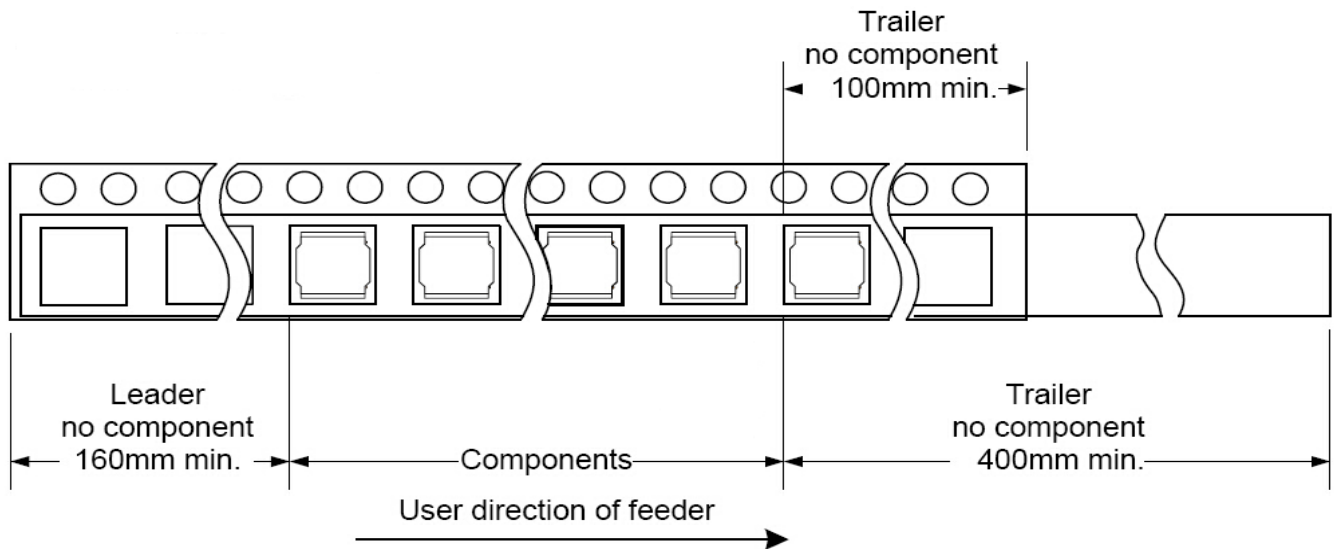
TYPE	W	A	B	C	D	E	P	K Ref	T	MPQ
YSPI105840	16±0.3	7.3±0.1	7.5±0.1	6.75	7.5±0.1	5.5±0.1	12.0±0.1	5.7	0.40±0.05	1000

■ Reel Dimensions(Unit:mm)

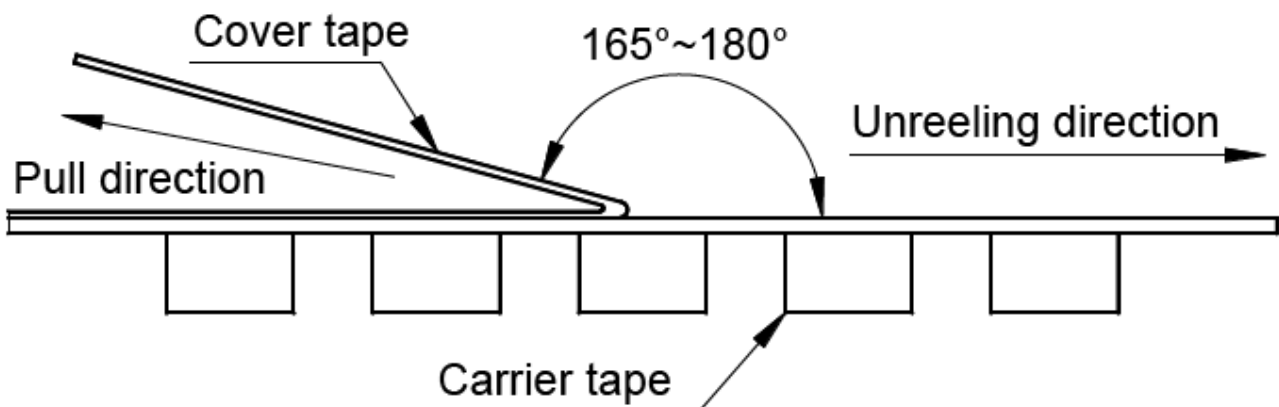


TYPE	W	W1	W2	W3	A	B	C	D
YSPI105840	330±2.0	16.4±2.0	22.4MAX	15.9 Min	13.0±0.50	21.0±0.80	2.0±0.50	100 Min

■ Direction of rolling



■ Cover tape peel off condition



Cover tape peel force shall be 0.1N to 1.3N.

Reference peel speed 300±10mm/min.